

Data sheet acquired from Harris Semiconductor

CD40107B Types

CMOS Dual 2-Input NAND Buffer/Driver

High-Voltage Type (20-Volt Rating)

■ CD40107B is a dual 2-input NAND buffer/driver containing two independent 2-input NAND buffers with open-drain single n-channel transistor outputs. This device features a wired-OR capability and high output sink current capability (136 mA typ. at VDD = 10 V, VDS = 1 V). The CD40107B is supplied in the 8-lead dual-in-line plastic (Mini-DIP) package (E suffix), 14-lead hermetic frit-seal ceramic package (F suffix), and in chip form (H suffix).

Features:

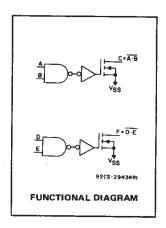
- 32 times standard B-Series output current drive sinking capability — 136 mA typ.
 VDD = 10 V, VDS = 1 V
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- 5-V, 10-V, and 15-V parametric ratings
- Noise margin, full package temperature range, R_L to V_{DD} = 10 kΩ:

1 V at V_{DD} = 5 V

2 V at V_{DD} = 10 V

2.5 V at V_{DD} = 15 V

Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



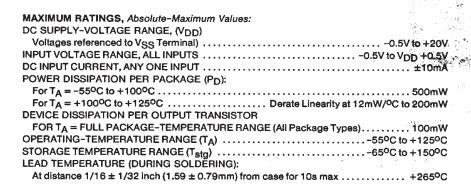


*Requires external pull-up resistor (RL) to VDD. #Without pull-up resistor (3-state).

Fig.1 - Schematic diagram of CD40107B (one of 2 gates)

Applications

- Driving relays, lamps, LEDs
- Line driver
- Level shifter (up or down)



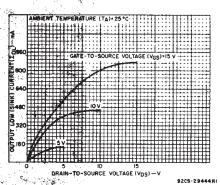


Fig.2 - Typical output low (sink) current characteristics.

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIF			
CHARACTERISTIC	MIN.	MAX.	UNITS	
Supply-Voltage Range (For TA=			-	
Full Package-Temperature Range)	3	18	v	

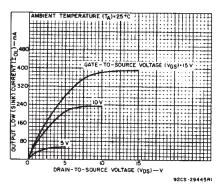


Fig.3 — Minimum output low (sink) current characteristics.

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DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C, C_L = 50 pF, Input t_r , t_f = 20 ns

	TEST CONDIT	LIMITS		T		
CHARACTERISTIC		V _{DD} Volts	Тур.	Max.	UNITS	
Propagation Delay: High-to-Low, tpHL	RL* = 120 Ω	5	100	200		
		10	45	90	ns	
		15	30	60		
Low-to-High, tPLH	RL* = 120 Ω	5	100	200	1. 19	
		10	60	120	ns	
		15	50	100		
Transition Time: High-to-Low, t _{THL}	RL* = 120 Ω	5	50	100		
		10	20	40	ns	
		15	10	20	1	
Low-to-High, t _{TLH}		5	50	100	ns	
	R _L * = 120 Ω	10	35	70		
		15	25	50		
Average Input Capacitance, CIN	Any Input		5	7.5	pF	
Average Output Capacitance, COUT	Any Output		30	-	pF	

^{*} R_L is external pull-up resistor to V_{DD}.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER-	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)						UNITS	
13110	Vo	VIN	V_{DD}	+25]		
	(V)	(V)	(V)	-55	-40	+85	+125	Min.	Тур.	Max.	
Quiescent Device Current IDD Max.	_	0,5	5	1	1	30	30	_	0.02	1	μА
		0,10	10	2	2	60	60	-	0.02	2	
	_	0,15	15	4	4	120	120	l. –	0.02	4	
	_	0,20	20	20	20	600	600	_	0.04	20	
Outout Law	0.4	0,5	5	21	20	14	12	16	32	_	
Output Low (Sink) Current	1	0,5	5	44	42	30	25	34	68	<u> </u>	
IOL Min.	0.5	0,10	10	49	46	32	28	37	74	_	mA
IOL IIIIII	1	0,10	10	89	85	60	51	68	136	-	
	0.5	0,15	15	66	63	44	38	50	100	-	
Output High (Source) Current IOH Min.	No Internal Pull-Up Device										
Input Low	4.5	-	5		1	.5		. —	_	1.5	٧
Voltage	9	_	10			3		_	-	3	
VIL Max.*	13.5		15			4		-	_	4	
Input High Voltage VIH Min.*	0.5,4.5	_	5		3	.5		3.5	_	_	
	1,9		10			7		7	_	_	
	1.5,13.5	-	15		11			11	_	_	
Input Current IIN Max.	-	0,18	18	±0.1	±0.1	±1	±1	_	±10 ⁻⁵	±0.1	μΑ
Output Leakage Current IOZ Max.	18	0,18	18	2	2	20	20	ı	10 ⁻⁴	2	μА

^{*} Measured with external pull-up resistor, R $_{L}$ = 10 $k\Omega$ to $V_{DD}.$

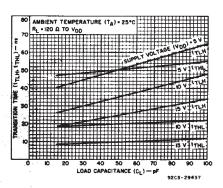


Fig.4 — Typical transition time as a function of load capacitance.

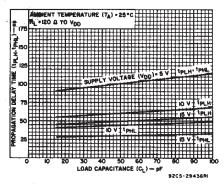


Fig.5 — Typical propagation delay time as a function of load capacitance.

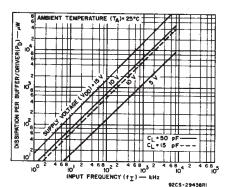


Fig.6 — Typical power dissipation as a function of input frequency.

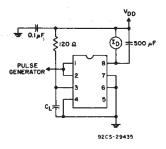
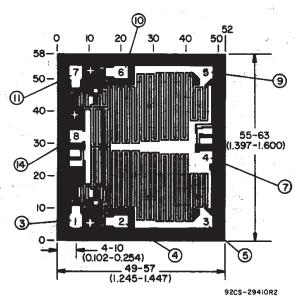


Fig. 7 — Power-dissipation test circuit for CD40107BE.

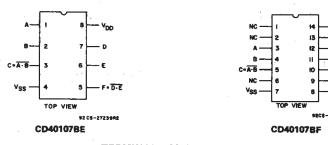
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NOTE: NOS. IN PADS FOR CD40107BE NOS. OUTSIDE CHIP FOR CD40107BF

Dimensions and Pad Layout for CD401078H.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).



TERMINAL ASSIGNMENTS

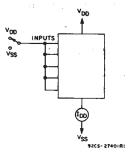


Fig.8 - Quiescent-device current test circuit.

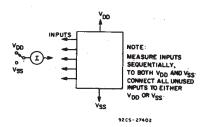


Fig. 9 - Input-current test circuit.

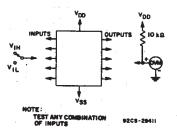


Fig. 10 — Input-voltage test circuit.

Special Considerations for CD40107B

1. Limiting Capacitive Currents for CL > 500 pF, $V_{DD} >$ 15 V.

For V_{DD} > 15 V, and load capacitance (C_L) from output to ground > 500 pF, an external 25 Ω series limiting resistor should be inserted between the output terminal and C_L. No external resistor is necessary if C_L < 500 pF or V_{DD} < 15 V.

2. Driving Inductive Loads

When using the CD40107B to drive inductive loads, the load should be shunted with a diode to prevent high voltages from developing across the CD40107B output.

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